



(43) **Pub. Date:** **Jun. 27, 2024**

A circuit board according to an embodiment includes: a first insulating layer that does not include a reinforcing material; a conductive pad that protrudes above a surface of the first insulating layer; a dam that protrudes from the surface of the first insulating layer and is disposed outside a region where the conductive pad is disposed on a plane; and a second insulating layer that is disposed below the first insulating layer and includes a reinforcing material. A height of the dam based on the surface of the first insulating layer is higher than a height of the conductive pad.

Dec. 26, 2022 (KR) 10-2022-0184351

